PATENT ABSTRACTS OF JAPAN

(11)Publication number :

09-171992

(43)Date of publication of application: 30.06.1997

(51)Int.CI.

H01L 21/3065

(21)Application number : 07-332183

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(22)Date of filing: 20.12.1995

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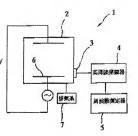
(54) DRY ETCHING APPARATUS

(57)Abstract:

PROBLEM TO BE SOLVED: To exactly determine cleaning-start time and cleaning-end time.

SOLUTION: An etching apparatus 1 has a sensor in an

determined based on the volume of deposition of reaction product deposited on the sensor while a plurality of substrates are etched by using this dry etching apparatus 1. The change of the volume of deposition of the reaction product is measured while the etching apparatus 1 is subjected to plasma cleaning, and cleaning-end time is determined based on a point where the change of the volume of deposition has become small.



LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration] [Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's

decision of rejection]

[Date of requesting appeal against examiner's

decision of rejection]

[Date of extinction of right]